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(12) United States Design Patent

Oba

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(54) **SEMICONDUCTOR ELEMENT**

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(73) Assignee: **Sony Corporation**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/079,664**

(22) Filed: **Nov. 20, 1997**

(30) **Foreign Application Priority Data**

May 21, 1997 (JP) 9-55010

(51) **LOC (7) Cl.** **14-02**
(52) **U.S. Cl.** **D14/117**; D13/182
(58) **Field of Search** ..... D13/182, 199; D14/117, 114; 84/477 R; 235/380–382, 492; 257/459, 465, 466, 618, 623, 679

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(57) **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a semiconductor element showing my new design;
FIG. **2** is a top plan view thereof;
FIG. **3** is a left side elevational view thereof;
FIG. **4** is a front elevational view thereof;
FIG. **5** is a bottom plan view thereof;
FIG. **6** is a right side elevational view thereof;
FIG. **7** is a rear elevational view thereof; and,
FIG. **8** is reference perspective view thereof in the using condition.
Portions in broken lines are for illustrative purposes only and form no part of claimed design.

1 Claim, 4 Drawing Sheets

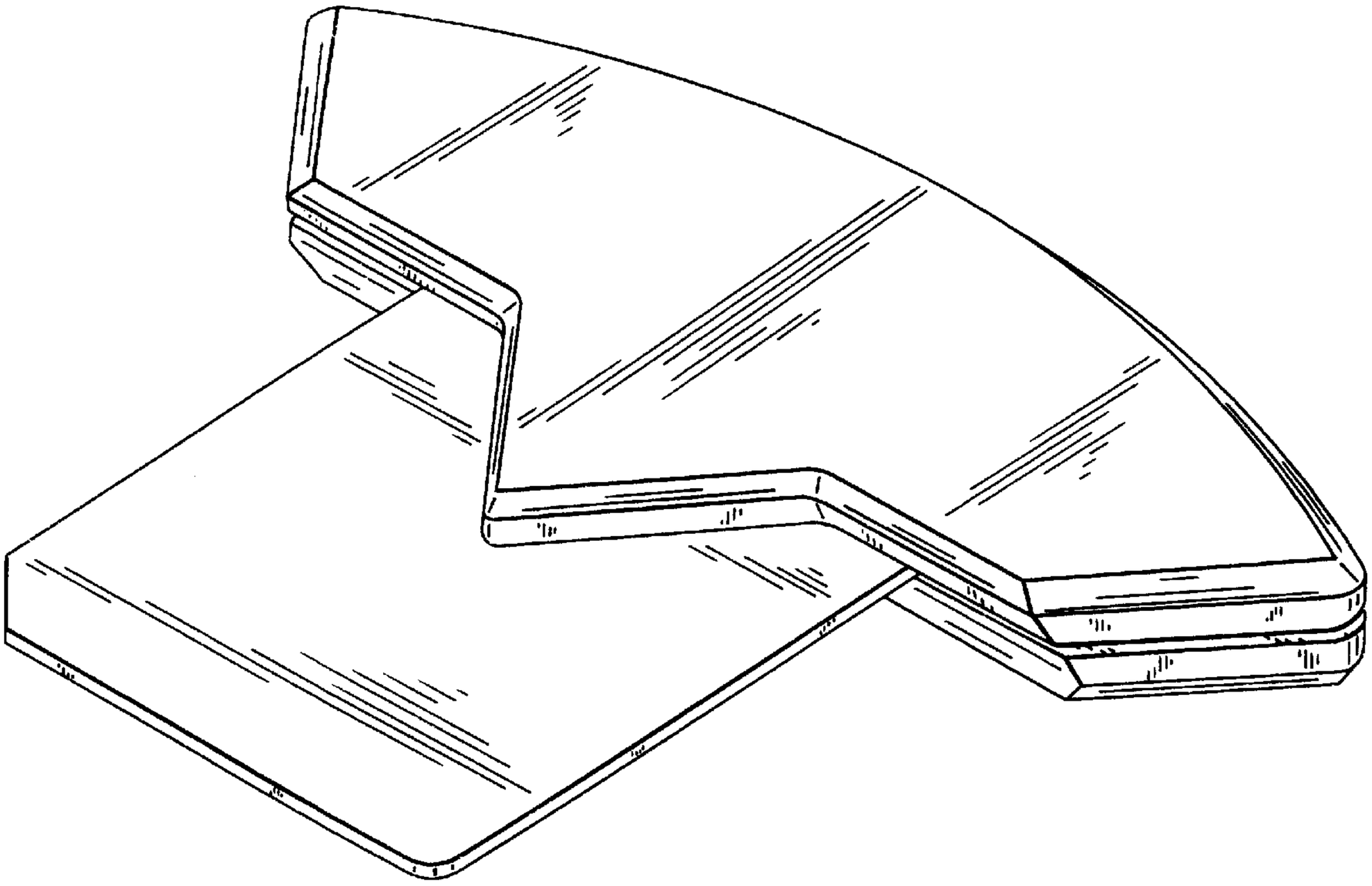

FIG. 1

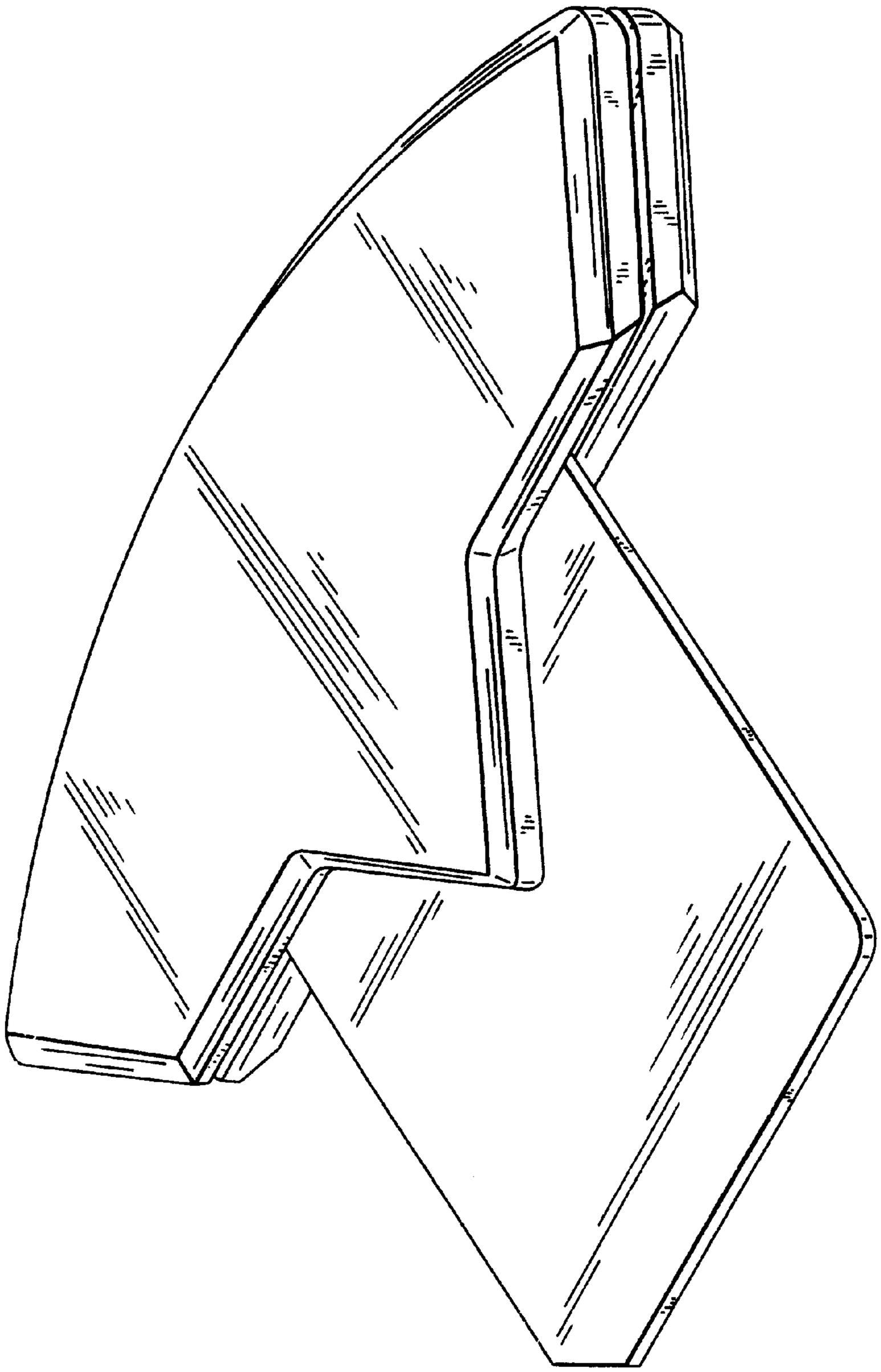

FIG. 6

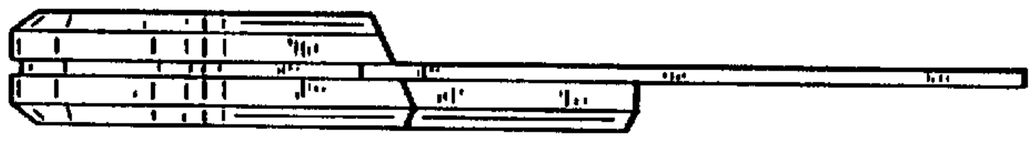

FIG.2

FIG. 5

FIG. 3

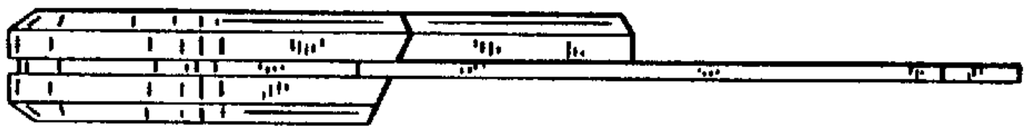

FIG. 7

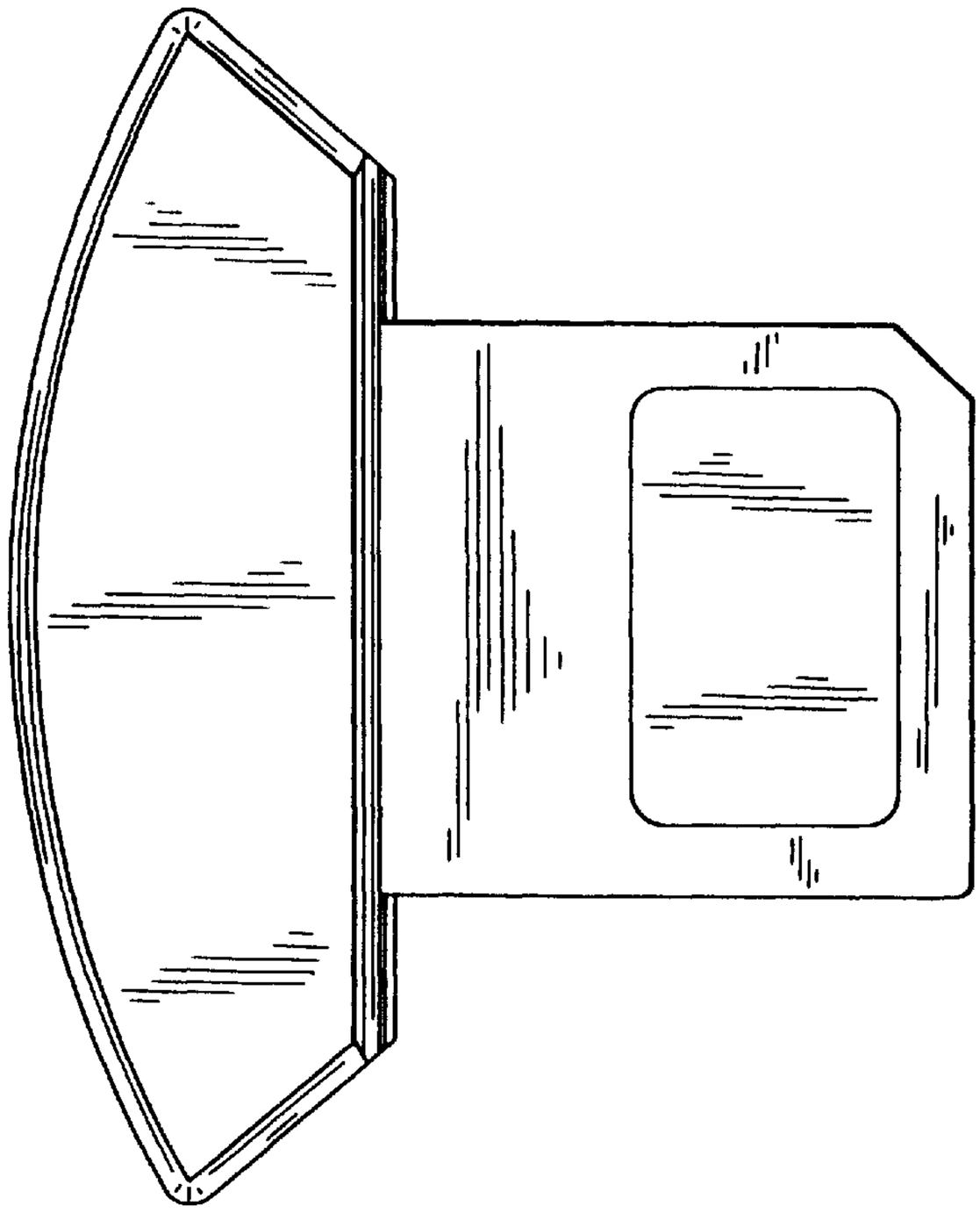

FIG. 4

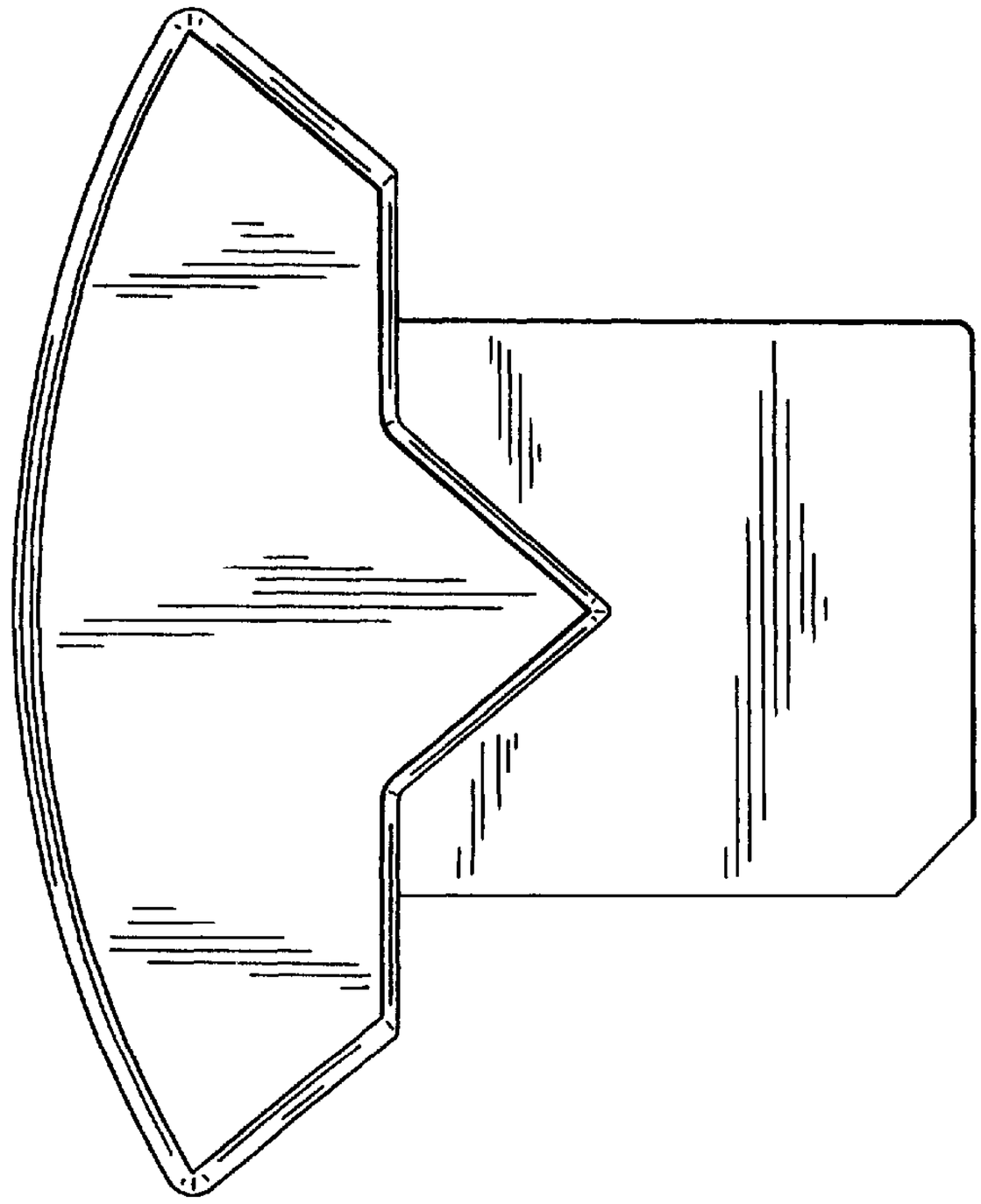

FIG. 8